



Material Content Data Sheet



Sales Product Name		BGT 24LTR11N16 E6327		Issued		23. January 2018		
MA#		MA001398694						
Package		PG-TSNP-16-9		Weight*		11.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.838	7.05	7.05	70531	70531
leadframe	non noble metal	chromium	7440-47-3	0.011	0.09		934	
	non noble metal	tin	7440-31-5	0.009	0.08		778	
	non noble metal	zinc	7440-66-6	0.007	0.06		623	
wire	non noble metal	copper	7440-50-8	3.669	30.89	31.12	308949	311284
	noble metal	gold	7440-57-5	0.083	0.70	0.70	7009	7009
encapsulation	organic material	carbon black	1333-86-4	0.033	0.27		2738	
	plastics	epoxy resin	-	0.943	7.94		79398	
	inorganic material	silicondioxide	60676-86-0	5.528	46.55	54.76	465437	547573
leadfinish	non noble metal	tin	7440-31-5	0.234	1.97	1.97	19665	19665
plating	noble metal	silver	7440-22-4	0.172	1.45	1.45	14497	14497
glue	plastics	epoxy resin	-	0.070	0.59		5888	
	noble metal	silver	7440-22-4	0.280	2.36	2.95	23553	29441
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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